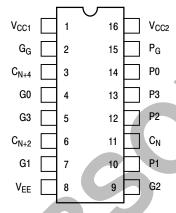
Look-Ahead Carry Block

The MC10H179 is a functional/pinout duplication of the standard MECL 10K part, with 100% improvement in propagation delay and no increase in power supply current.

- Power Dissipation, 300 mW Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



ON Semiconductor

http://onsemi.com

MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





1

PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H179L	CDIP-16	25 Units/Rail
MC10H179P	PDIP-16	25 Units/Rail
MC10H179FN	PLCC-20	46 Units/Rail

MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V _{EE}	Power Supply (V _{CC} = 0)	-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)	0 to V _{EE}	Vdc
l _{out}	Output Current - Continuous - Surge	50 100	mA
T _A	Operating Temperature Range	0 to +75	°C
T _{stg}	Storage Temperature Range - Plastic - Ceramic	-55 to +150 -55 to +165	°,

ELECTRICAL CHARACTERISTICS (V_{EE} = -5.2 V ±5%) (See Note 1.)

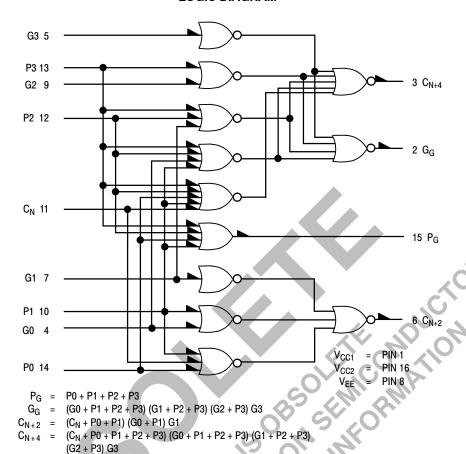
		0	0	25	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
Ι _Ε	Power Supply Current	-	79	-	72	-	79	mA
linH	Input Current High Pins 5 and 9 Pins 4, 7 and 11 Pin 14 Pin 12 Pins 10 and 13	- - - -	465 545 705 790 870		275 320 415 465 510	- - -	275 320 415 465 510	μΑ
l _{inL}	Input Current Low	0.5	7	0.5	_	0.3	_	μΑ
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V_{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

AC PARAMETERS

t _{pd}	Propagation Delay P to P _G G, P, C _n to C _n or G _G	0.4	1.4 0.4 2.3 0.7	1.5 2.4	0.5 0.8	1.7 2.6	ns
t _r	Rise Time	0.5	1.7 0.5	1.8	0.5	1.9	ns
t _f	Fall Time	0.5	1.7 0.5	1.8	0.5	1.9	ns

^{1.} Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts.

LOGIC DIAGRAM



TYPICAL APPLICATIONS

The MC10H179 is a high-speed, low-power, standard MECL complex function that is designed to perform the look-ahead carry function. This device can be used with the MC10H181 4-bit ALU directly, or with the MC10H180 dual arithmetic unit in any computer, instrumentation or digital communication application requiring high speed arithmetic operation on long words.

When used with the MC10H181, the MC10H179 performs a second order or higher look-ahead. Figure 2

shows a 16-bit look-ahead carry arithmetic unit. Second order carry is valuable for longer binary words. As an example, addition of two 32-bit words is improved from 30 nanoseconds with ripple-carry techniques. A block diagram of a 32-bit ALU is shown in Figure 1. The MC10H179 may also be used in many other applications. It can, for example, reduce system package count when used to generate functions of several variables.

FIGURE 1 - 32-BIT ALU WITH CARRY LOOK-AHEAD

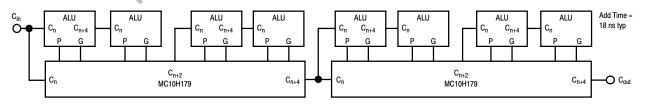
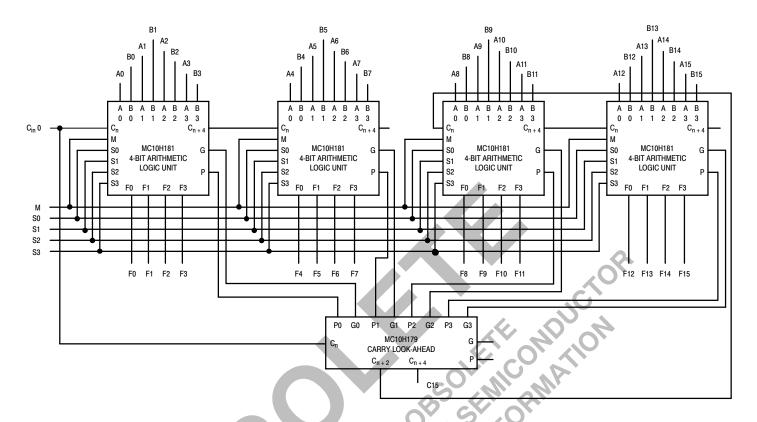


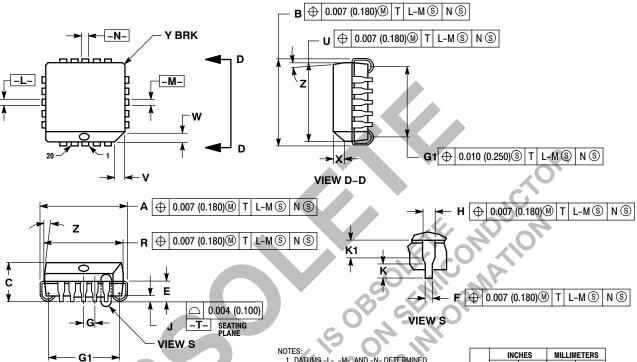
FIGURE 2 - 16-BIT FULL LOOK-AHEAD CARRY ARITHMETIC LOGIC UNIT



PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



0.010 (0.250) T L-M N N

- IOTES:

 1. DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC
 BODY AT MOLD PARTING LINE.

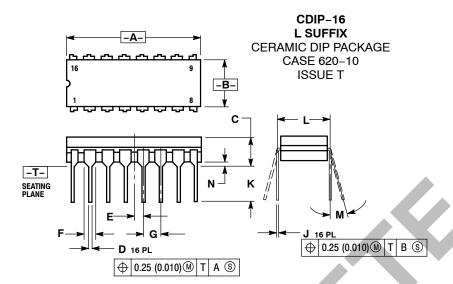
 2. DIMENSION 61, TRUE POSITION TO BE
 MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
 FLASH: ALLOWABLE MOLD FLASH IS 0.010 (0.250)
 DED SIGN PER SIDE.
 DIMENSIONING AND TOLERANCING PER ANSI

- 714.5M, 1982.
 5. CONTROLLING DIMENSION: INCH.
 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO .0.12 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP
- AND BOTTOM OF THE PLASTIC BODY.
 DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Е	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Χ	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2 °	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

PACKAGE DIMENSIONS

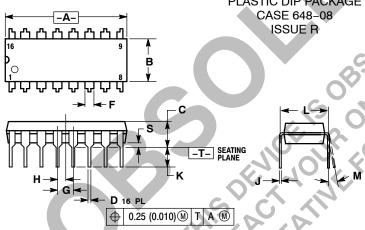


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
- DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050 BSC		1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100 BSC		2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62 BSC		
M	0°	15°	0°	15°	
N	0.020	0.040	0.51	1.01	





NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MIN MAX		MAX	
A	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015 0.021		0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100 BSC		2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

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